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(54) ELECTRONIC DEVICE AND METHOD OF MANUFACTURING THE SAME

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(57)ABSTRACT

The present disclosure provides an electronic device and a method of manufacturing the same. The electronic device includes a first redistribution structure and a first encapsulant. The first encapsulant supports the first redistribution structure and is configured to function as a first reinforcement to provide a second redistribution structure. The redistribution structure has a plurality of conductive layers disposed over the first redistribution structure.



